

L Number	Hits	Search Text	DB	Time stamp
1	0	(29/852).ccls. and (grid adj array adj package) and (housing or enclosing) and (semiconductor or die) and substrate and ((project or projecting or extend or extending or space or spacing) with lead)	USPAT; US-PGPUB; IBM_TDB	2004/07/06 09:26
2	0	(29/846,852).ccls. and (solder adj bump) with ((lead adj free) or leadfree)	USPAT; US-PGPUB; IBM_TDB	2004/07/06 09:28
3	6	(29/846,852).ccls. and (ball or bump) with ((lead adj free) or leadfree)	USPAT; US-PGPUB; IBM_TDB	2004/07/06 09:29
4	2	(427/96,97,98).ccls. and (ball or bump) with ((lead adj free) or leadfree)	USPAT; US-PGPUB; IBM_TDB	2004/07/06 09:29
-	1069	29/832.ccls.	USPAT; US-PGPUB; IBM_TDB	2003/02/20 10:35
-	1821	grid adj array adj package	USPAT; US-PGPUB; IBM_TDB	2003/02/20 10:36
-	368	(grid adj array adj package) and (housing or enclosing)	USPAT; US-PGPUB; IBM_TDB	2003/02/20 10:36
-	262	(grid adj array adj package) and (housing or enclosing) and (semiconductor or die)	USPAT; US-PGPUB; IBM_TDB	2003/02/20 10:37
-	247	(method or process) and (grid adj array adj package) and (housing or enclosing) and (semiconductor or die)	USPAT; US-PGPUB; IBM_TDB	2003/02/20 10:44
-	191	(method or process) and (grid adj array adj package) and (housing or enclosing) and (semiconductor or die) and substrate	USPAT; US-PGPUB; IBM_TDB	2003/02/20 10:47
-	168	(method or process) and (grid adj array adj package) and (housing or enclosing) and (semiconductor or die) and substrate and lead	USPAT; US-PGPUB; IBM_TDB	2003/02/20 10:48
-	63	(method or process) and (grid adj array adj package) and (housing or enclosing) and (semiconductor or die) and substrate and ((project or projecting or extend or extending or space or spacing) with lead)	USPAT; US-PGPUB; IBM_TDB	2003/02/20 10:51
-	72	(method or process) and (grid adj array adj package) and (housing or enclosing) and (semiconductor or die) and substrate and ((project or projecting or extend or extending or space or spacing) with lead)	USPAT; US-PGPUB; IBM_TDB	2003/02/20 17:53
-	0	20020134582.URPN.	USPAT	2003/02/20 14:09
-	41	("2905873" "4398208" "4461924" "4514752" "4667219" "4698663" "4700473" "4706811" "4737395" "4771159" "4771537" "4791075" "4816426" "4821151" "4835598" "4845313" "4868638" "4868639" "4926241" "4939316" "4965227" "4990720" "5006922" "5045914" "5046971" "5065228" "5065281" "5098864" "5102829" "5108955" "5124884" "5144412" "5148265" "5148266" "5151771" "5153379" "5166772" "5189261" "5216278" "5241133" "5267684").PN.	USPAT	2003/02/20 10:57
-	131	(method or process) and (pin adj grid adj array) and (housing or enclosing) and (semiconductor or die) and substrate and ((project or projecting or extend or extending or space or spacing) with lead)	USPAT; US-PGPUB; IBM_TDB	2003/02/20 12:35

-	18	((method or process) with (pin adj grid adj array)) and (housing or enclosing) and (semiconductor or die) and substrate and ((project or projecting or extend or extending or space or spacing) with lead)	USPAT; US-PGPUB; IBM_TDB	2003/02/20 11:54
-	41	("2905873" "4398208" "4461924" "4514752" "4667219" "4698663" "4700473" "4706811" "4737395" "4771159" "4771537" "4791075" "4816426" "4821151" "4835598" "4845313" "4868638" "4868639" "4926241" "4939316" "4965227" "4990720" "5006922" "5045914" "5046971" "5065228" "5065281" "5098864" "5102829" "5108955" "5124884" "5144412" "5148265" "5148266" "5151771" "5153379" "5166772" "5189261" "5216278" "5241133" "5267684").PN.	USPAT	2003/02/20 11:45
-	0	((method or process) with (land adj grid adj array adj package)) and (housing or enclosing) and (semiconductor or die) and substrate and ((project or projecting or extend or extending or space or spacing) with lead)	USPAT; US-PGPUB; IBM_TDB	2003/02/20 14:34
-	93	((method or process) and (land adj grid adj array adj package))	USPAT; US-PGPUB; IBM_TDB	2003/02/20 11:55
-	19	((method or process) with (land adj grid adj array adj package))	USPAT; US-PGPUB; IBM_TDB	2003/02/20 11:55
-	6	("5633204" "5637832" "5714803" "5736790" "5753973" "5920770").PN.	USPAT	2003/02/20 12:31
-	12	(method or process) and (pin adj grid adj array) and (housing or enclosing) and (semiconductor or die) and substrate and ((project or projecting or extend or extending or space or spacing) with lead) and ((photoresist or protective) adj (film or layer))	USPAT; US-PGPUB; IBM_TDB	2003/02/20 12:53
-	10	("3676292" "4225900" "4301324" "4313026" "4320438" "4385202" "4410927" "4491622" "4513355" "4622433").PN.	USPAT	2003/02/20 12:45
-	7	("3436604" "3436606" "3651434" "3676748" "3808475" "3926746" "4150420").PN.	USPAT	2003/02/20 12:47
-	59	4320438.URPN.	USPAT	2003/02/20 12:48
-	0	(method or process) and (pin adj grid adj array) and (housing or enclosing) and (semiconductor or die) and substrate and ((project or projecting or extend or extending or space or spacing) with lead with plating) and ((photoresist or protective) adj (film or layer))	USPAT; US-PGPUB; IBM_TDB	2003/02/20 12:54
-	1	(method or process) and (grid adj array adj package) and (housing or enclosing) and (semiconductor or die) and substrate and ((project or projecting or extend or extending or space or spacing) with lead with plating) and ((photoresist or protective) adj (film or layer))	USPAT; US-PGPUB; IBM_TDB	2003/02/20 12:57
-	1	(method or process) and (grid adj array adj package) and (housing or enclosing) and (semiconductor or die) and substrate and ((project or projecting or extend or extending or space or spacing) with lead with plating)	USPAT; US-PGPUB; IBM_TDB	2003/02/20 12:55

-	8	(method or process) and (grid adj array adj package) and (housing or enclosing) and (semiconductor or die) and substrate and (lead with plating)	USPAT; US-PGPUB; IBM_TDB	2003/02/20 12:55
-	1	(method or process) and (grid adj array adj package) and (semiconductor or die) and substrate and ((project or projecting or extend or extending or space or spacing) with lead with plating) and ((photoresist or protective) adj (film or layer))	USPAT; US-PGPUB; IBM_TDB	2003/02/20 12:57
-	24	(method or process) and (grid adj array adj package) and (semiconductor or die) and substrate and (lead with plating) and ((photoresist or protective) adj (film or layer))	USPAT; US-PGPUB; IBM_TDB	2003/02/20 13:15
-	27	(grid adj array adj package) and (lead with plating) and ((photoresist or protective) adj (film or layer))	USPAT; US-PGPUB; IBM_TDB	2003/02/20 13:30
-	27	(grid adj array adj package) and (lead with (electroplating or plating)) and ((photoresist or protective) adj (film or layer))	USPAT; US-PGPUB; IBM_TDB	2003/02/20 13:38
-	77	(grid adj array adj package) and (electroplating or plating) and ((photoresist or protective) adj (film or layer))	USPAT; US-PGPUB; IBM_TDB	2003/02/20 13:39
-	2	("5977633" "6201292").PN.	USPAT	2003/02/20 13:53
-	6	("4701592" "5049405" "5523543" "5639695" "5989935" "6064111").PN.	USPAT	2003/02/20 14:00
-	1	6262477.pn. and (electroplating or plating)	USPAT	2003/02/20 14:10
-	41	("2905873" "4398208" "4461924" "4514752" "4667219" "4698663" "4700473" "4706811" "4737395" "4771159" "4771537" "4791075" "4816426" "4821151" "4835598" "4845313" "4868638" "4868639" "4926241" "4939316" "4965227" "4990720" "5006922" "5045914" "5046971" "5065228" "5065281" "5098864" "5102829" "5108955" "5124884" "5144412" "5148265" "5148266" "5151771" "5153379" "5166772" "5189261" "5216278" "5241133" "5267684").PN.	USPAT	2003/02/20 14:24
-	10	("3676292" "4225900" "4301324" "4313026" "4320438" "4385202" "4410927" "4491622" "4513355" "4622433").PN.	USPAT	2003/02/20 14:30
-	20	4821151.URPN.	USPAT	2003/02/20 14:49
-	10	((method or process) with (land adj grid adj array adj package)) and (plating or electroplating)	USPAT; US-PGPUB; IBM_TDB	2003/02/20 14:35
-	6	("5633204" "5637832" "5714803" "5736790" "5753973" "5920770").PN.	USPAT	2003/02/20 14:41
-	1	6162664.pn. and substrate	USPAT	2003/02/20 16:11
-	1	6162664.pn. and substrate and plating	USPAT	2003/02/20 16:11
-	4	(438/126,613,614).ccls. and (grid adj array adj package) and (housing or enclosing) and (semiconductor or die) and substrate and ((project or projecting or extend or extending or space or spacing) with lead)	USPAT; US-PGPUB; IBM_TDB	2003/02/20 17:59

-	3	(29/832,837,846,854,855,856).ccls. and (grid adj array adj package) and (housing or enclosing) and (semiconductor or die) and substrate and ((project or projecting or extend or extending or space or spacing) with lead)	USPAT; US-PGPUB; IBM_TDB	2003/02/20 17:59
-	221	integrated adj circuit adj package adj method	USPAT; US-PGPUB; IBM_TDB	2003/08/25 13:52
-	1	(integrated adj circuit adj package adj method) and (integrated adj circuits adj high adj pin adj lead)	USPAT; US-PGPUB; IBM_TDB	2003/08/25 13:56
-	4	(celaya-phillip-c).in.	USPAT; US-PGPUB; IBM_TDB	2004/07/02 15:28
-	1	(donley-james-s).in.	USPAT; US-PGPUB; IBM_TDB	2004/07/02 15:29
-	2	(Germain-Stephen-C-St).in.	USPAT; US-PGPUB; IBM_TDB	2004/07/02 15:29
-	247	(solder adj bump) with nickel	USPAT; US-PGPUB; IBM_TDB	2004/07/05 10:49
-	88	(solder adj bump) with ((lead adj free) or leadfree)	USPAT; US-PGPUB; IBM_TDB	2004/07/05 10:50
-	3	(solder adj bump) with ((lead adj free) or leadfree) with plat\$3	USPAT; US-PGPUB; IBM_TDB	2004/07/05 10:51
-	9	(solder adj bump) with ((lead adj free) or leadfree) same plat\$3	USPAT; US-PGPUB; IBM_TDB	2004/07/05 10:53
-	16	(bump) with ((lead adj free) or leadfree) same plat\$3	USPAT; US-PGPUB; IBM_TDB	2004/07/05 10:53